

G138K

N-CHANNEL ENHANCEMENT MODE POWER MOSFET

BVDSS	50V
RDS(ON)	2Ω
ID	640mA

Description

The G138K utilized advanced processing techniques to achieve the lowest possible on-resistance, extremely efficient and cost-effectiveness device.

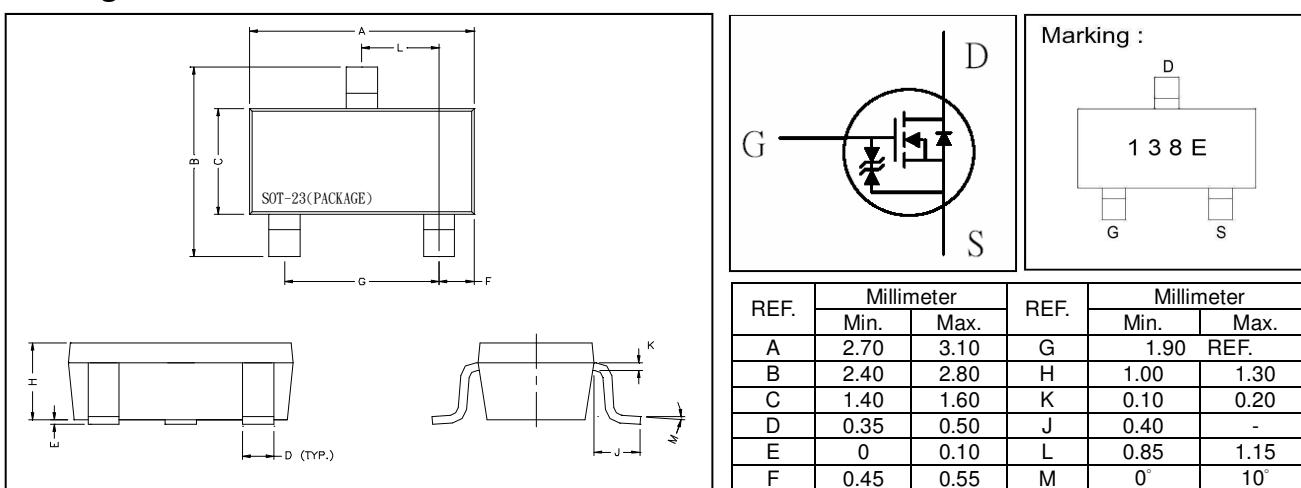
The G138K is universally used for all commercial-industrial applications.

Features

- *Simple Drive Requirement

- *Small Package Outline

- *RoHS Compliant

Package Dimensions**Absolute Maximum Ratings**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V _{DS}	50	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current ³ , V _{GS} @10V	I _D @T _A =25°C	640	mA
Continuous Drain Current ³ , V _{GS} @10V	I _D @T _A =70°C	500	mA
Pulsed Drain Current ^{1,2}	I _{DM}	950	mA
Power Dissipation	P _D @T _A =25°C	1.38	W
Linear Derating Factor		0.01	W/°C
Operating Junction and Storage Temperature Range	T _j , T _{stg}	-55 ~ +150	°C

Thermal Data

Parameter	Symbol	Ratings	Unit
Thermal Resistance Junction-ambient ³ Max.	R _{thj-a}	90	°C/W

Electrical Characteristics($T_j = 25^\circ\text{C}$ Unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV_{DSS}	50	-	-	V	$\text{V}_{\text{GS}}=0$, $\text{I}_D=250\mu\text{A}$
Breakdown Voltage Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}} / \Delta T_j$	-	0.06	-	V/ $^\circ\text{C}$	Reference to 25°C , $\text{I}_D=1\text{mA}$
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	0.5	-	2.0	V	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}$, $\text{I}_D=1\text{mA}$
Forward Transconductance	g_{fs}	-	600	-	mS	$\text{V}_{\text{DS}}=10\text{V}$, $\text{I}_D=600\text{mA}$
Gate-Source Leakage Current	I_{GSS}	-	-	± 10	μA	$\text{V}_{\text{GS}}= \pm 20\text{V}$
Drain-Source Leakage Current($T_j=25^\circ\text{C}$)	I_{DSS}	-	-	1	μA	$\text{V}_{\text{DS}}=50\text{V}$, $\text{V}_{\text{GS}}=0$
Drain-Source Leakage Current($T_j=70^\circ\text{C}$)		-	-	100	μA	$\text{V}_{\text{DS}}=40\text{V}$, $\text{V}_{\text{GS}}=0$
Static Drain-Source On-Resistance	$\text{R}_{\text{DS}(\text{ON})}$	-	-	2	Ω	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=500\text{mA}$
		-	-	4		$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=400\text{mA}$
Total Gate Charge ²	Q_g	-	1	1.6	nC	$\text{I}_D=600\text{mA}$ $\text{V}_{\text{DS}}=50\text{V}$ $\text{V}_{\text{GS}}=4.5\text{V}$
Gate-Source Charge	Q_{gs}	-	0.5	-		
Gate-Drain ("Miller") Change	Q_{gd}	-	0.5	-		
Turn-on Delay Time ²	$\text{T}_{\text{d}(\text{on})}$	-	12	-	ns	$\text{V}_{\text{DS}}=30\text{V}$ $\text{I}_D=600\text{mA}$ $\text{V}_{\text{GS}}=10\text{V}$ $\text{R}_G=3.3\Omega$ $\text{R}_D=52\Omega$
Rise Time	T_r	-	10	-		
Turn-off Delay Time	$\text{T}_{\text{d}(\text{off})}$	-	56	-		
Fall Time	T_f	-	29	-		
Input Capacitance	C_{iss}	-	32	50	pF	$\text{V}_{\text{GS}}=0\text{V}$ $\text{V}_{\text{DS}}=25\text{V}$ $f=1.0\text{MHz}$
Output Capacitance	C_{oss}	-	8	-		
Reverse Transfer Capacitance	C_{rss}	-	6	-		

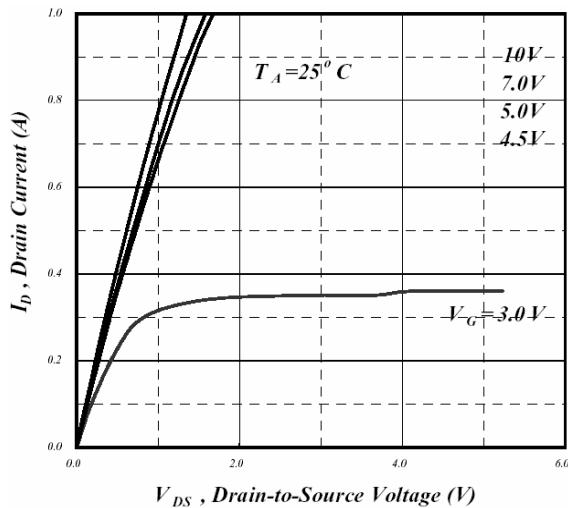
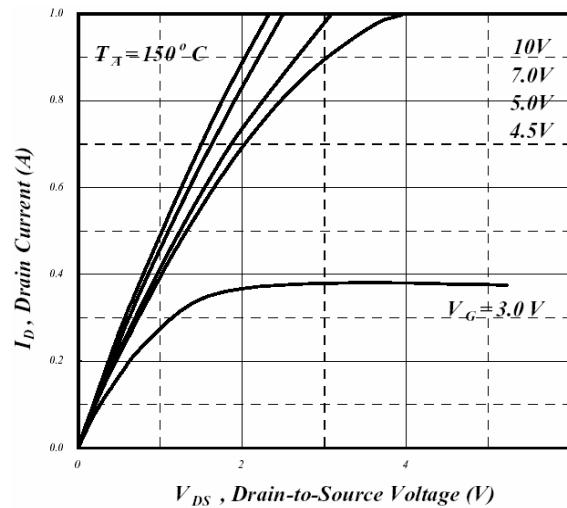
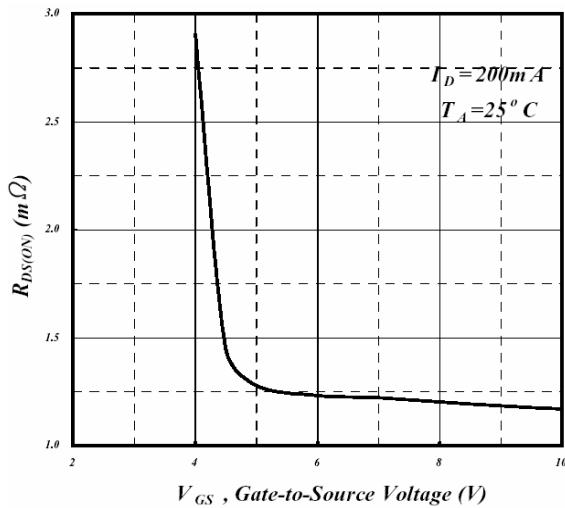
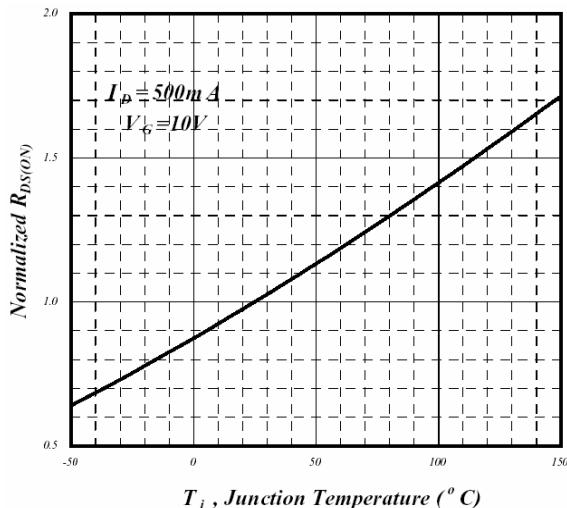
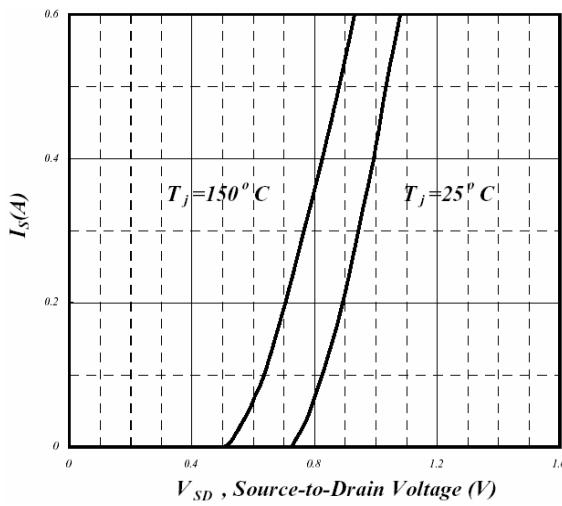
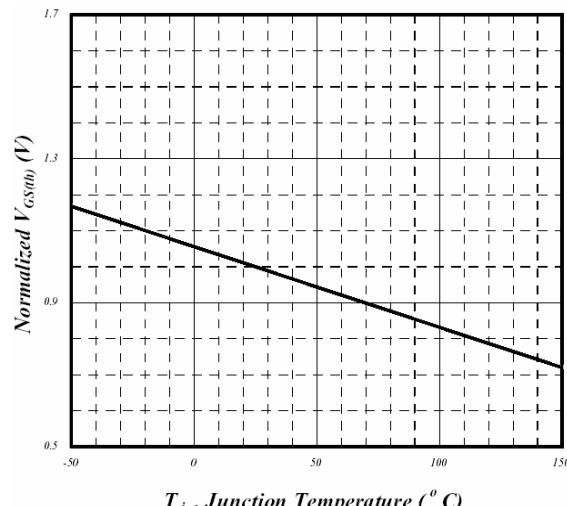
Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage ²	V_{SD}	-	-	1.2	V	$\text{I}_S=200\text{mA}$, $\text{V}_{\text{GS}}=0\text{V}$

Notes: 1. Pulse width limited by Max. junction temperature.

2. Pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.

3. Surface mounted on 1 in² copper pad of FR4 board; $270^\circ\text{C}/\text{W}$ when mounted on Min. copper pad.

Characteristics Curve**Fig 1. Typical Output Characteristics****Fig 2. Typical Output Characteristics****Fig 3. On-Resistance v.s. Gate Voltage****Fig 4. Normalized On-Resistance v.s. Junction Temperature****Fig 5. Forward Characteristics of Reverse Diode****Fig 6. Gate Threshold Voltage v.s. Junction Temperature**

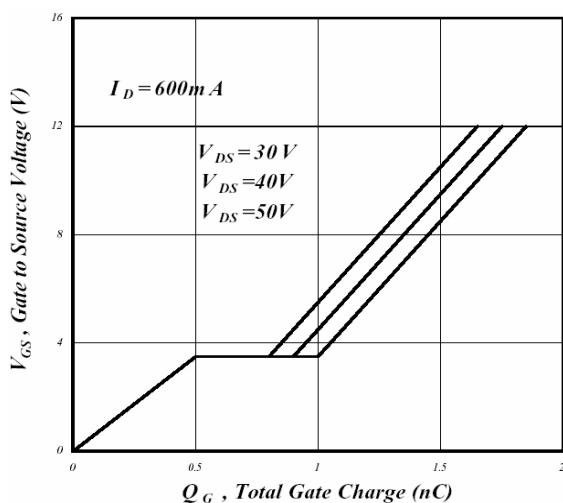


Fig 7. Gate Charge Characteristics

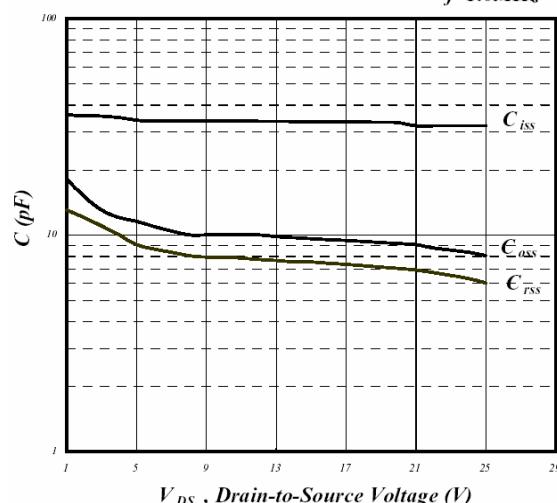


Fig 8. Typical Capacitance Characteristics

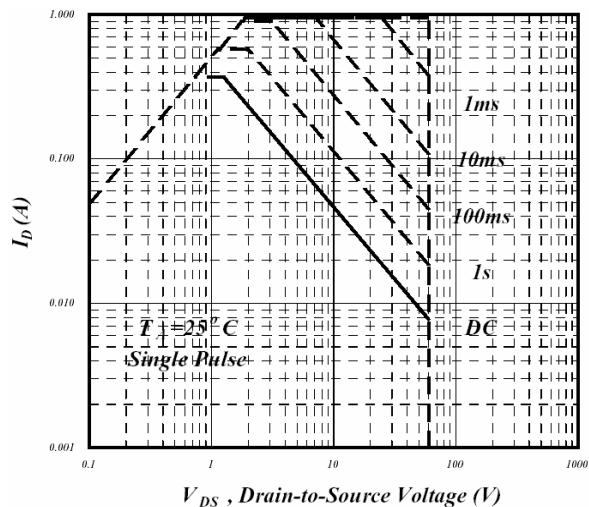


Fig 9. Maximum Safe Operating Area

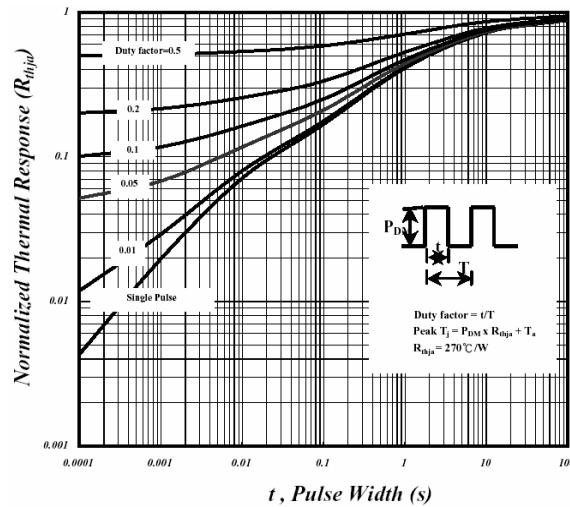


Fig 10. Effective Transient Thermal Impedance

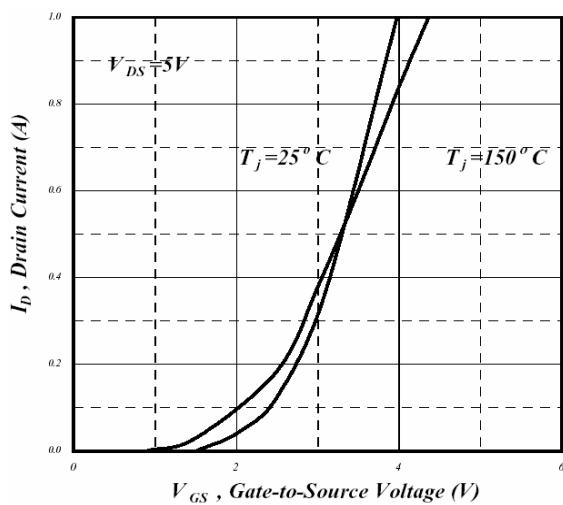


Fig 11. Transfer Characteristics

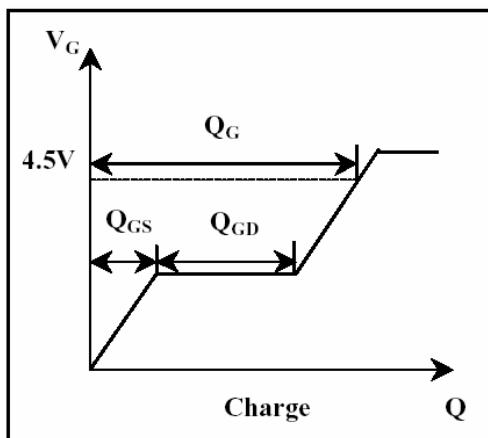


Fig 12. Gate Charge Waveform

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of GTM.
 - GTM reserves the right to make changes to its products without notice.
 - GTM semiconductor products are not warranted to be suitable for use in life-support Applications, or systems.
 - GTM assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.
- Head Office And Factory:**
- Taiwan:** No. 17-1 Tatung Rd. Fu Kou Hsin-Chu Industrial Park, Hsin-Chu, Taiwan, R. O. C.
TEL : 886-3-597-7061 FAX : 886-3-597-9220, 597-0785
 - China:** (201203) No.255, Jiang-Jiang Tsai-Lueng RD. , Pu-Dung-Hsin District, Shang-Hai City, China
TEL : 86-21-5895-7671 ~ 4 FAX : 86-21-38950165